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Substitute for form 1449A/PTO				<b>Complete if Known</b>	
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  (use as many sheets as necessary)				Application Number	Not Yet Assigned 10/668887
				Filing Date	Herewith
				First Named Inventor	Jurgen Musolf et al
				Group Art Unit	2831 2822
				Examiner Name	Nguyen
Sheet 1 of 1	Attorney Docket Number		844004-302		

Examiner Initials *	Cite No. <sup>1</sup>	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document
		Number - Kind Code <sup>2</sup> (if known)		
MT		US-5,476,836	12-19-1995	Eddy
		US-5,508,255	04-16-1998	Eddy
		US-5,843,870	12-01-1998	Wu et al.
		US-5,883,050	03-16-1999	Yun et al.

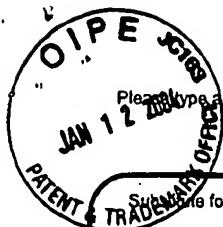
OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS			
Examiner Initials *	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
MT		ANGERER, H. et al., On the Electrodeposition of Hard Gold, Journal of Applied Electrochemistry, 9 (1979), pp 219-232	
		CHINTHAKINDI, A.K. et al., Stress Temperature Studies of Au/Al and Au/Zn Bimetallic Films, in press, pp 1-24	
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Examiner Signature	Michael Trim	Date Considered	10/25/04
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		Application Number	Not Yet Assigned 10/688887
		Filing Date	September 22, 2003
		First Named Inventor	MUSOLF et al.
		Group Art Unit	2831 2822
		Examiner Name	Nguyen
Sheet 1 of 1	Attorney Docket Number	844004-302	

Examiner Initials *	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY
	Number	Kind Code <sup>2</sup> (if known)		
MT	US-5613861		Smith et al.	03/25/97
	US-6229684	B1	Cowen et al.	05/08/01
	US-6361331	B2	Fork et al.	03/26/02
	US-6396677	B1	Chua et al.	05/28/02

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